

Page 1 of 3

	and lower or	necorney ror Pacer	ir Wbb	rication						
English Language Declaration										
As a below named inventor, I hereby declare that:										
My residence, post office address and citizenship are as stated below next to my name,										
l am originar, first	med and for which a	ole inventor (if only one na (if plural names are listed patent is sought on the inve	hala) -4	:						
the specification of	which									
(check one)										
is attached here	ito.	<u>,</u> .								
was filed on	June 30, 200	00		as						
Application Serial No. PCT/JP00/04335										
and was amended	on	-								
<u> </u>										
hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.										
I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).										
roreign application(_identified below any	(s) for patent or in foreign application f	s under Title 35, United Sta eventor's certificate listed or patent or inventor's certi- nich priority is claimed:	l below as	nd have also						
Prior Foreign Application(s) Priority Claimed										
244161/1999	Japan	31/Aug./1999	\square							
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No						
				. 🗆						
(Number)	(Country)	(Day/Month/Year Filed)	Yes	Мо						
(Number)	(Country)	(Day/Month/Year Filed)	Yes	№						
I hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, \$112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, \$1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:										

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	*					rage 2 of 3
(Application Se	rial No.)	(Filing Date	2)	(patented,	(Status) pending,	abandoned)
(Application Se	rial No.)	(Filing Date	2)	(patented,	(Status) pending,	abandoned)
statements were m are punishable by	on information ade with the kr fine or impriso that such will	ments made herein of and belief are bel nowledge that will nument, or both, und lful false statement thereon.	ieved to be ful false st ler Section	true; and atements a	further nd the li	that these ke so made
agent(s) to prosect Office connected William H. Logsdon Russell D. Orkin David C. Hanson Frederick B. Zies Richard L. Byrne Kent E. Baldauf	therewith. (11: 22,1363 23,024 enheim 19,438 28,498 25,826	nventor, I hereby ration and transact to name and registrates are successful to the	all busines ation numbers 33,059 34,219 10,424 35,034 36,216	ss in the P er) Lester N. Randall A. Jesse A. H. James G. P. Kent E. Ba	atent and Fortney Notzen irshman orcelli ldauf, Jr	38,141 36,882 40,016 33,757 36,082
		uilding, 436 Sevent				
Direct Telephone	calls to: (name	e and telephone num	<i>ber)</i> Russel	.l D. Orkin	(412) 47	1-8815
Full name of sole or	first inventor	Akira ICHIKAWA				
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Full name of second	joint inventor, if	any Kenichi WATAN	IARE			
Second inventor's sig	mature Kenje	chi Watanal	se	D	ate April	2, 2001
Residence	Tokyo, Japan	TPX,				
Citizenship	Japanese			- · · · · · · · · · · · · · · · · · · ·		
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	173-0001, Jap	oan				
(Supply similar inform	ation and signatur	e for third and subsequ	ment joint inv	entors.)	· · · · · · · · · · · · · · · · · · ·	
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